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OSHIMA(10) **Pub. No.: US 2022/0369453 A1**(43) **Pub. Date: Nov. 17, 2022**(54) **RADIO-FREQUENCY MODULE AND
COMMUNICATION DEVICE**(52) **U.S. Cl.**CPC *H05K 1/0243* (2013.01); *H05K 1/0216*
(2013.01); *H05K 2201/10734* (2013.01)(71) Applicant: **Murata Manufacturing Co., Ltd.**,
Kyoto (JP)(72) Inventor: **Takayuki OSHIMA**, Kyoto (JP)

(57)

ABSTRACT(21) Appl. No.: **17/815,987**(22) Filed: **Jul. 29, 2022****Related U.S. Application Data**(63) Continuation of application No. PCT/JP2020/
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There is provided a radio-frequency module and a communication device with which miniaturization can be achieved and quality deterioration can be suppressed. A radio-frequency module includes a mount board on which a ground terminal is disposed, a first chip, a second chip, and a cover (a shield cover). The first chip is disposed on the mount board. The second chip is disposed on the first chip. The cover covers at least a part of the first chip and at least a part of the second chip. The second chip has a first connection terminal (a ground terminal) on an opposite side from the first chip in a thickness direction of the mount board. The cover includes a shield layer connected to the ground terminal disposed on the mount board. The first connection terminal is connected to the shield layer.

